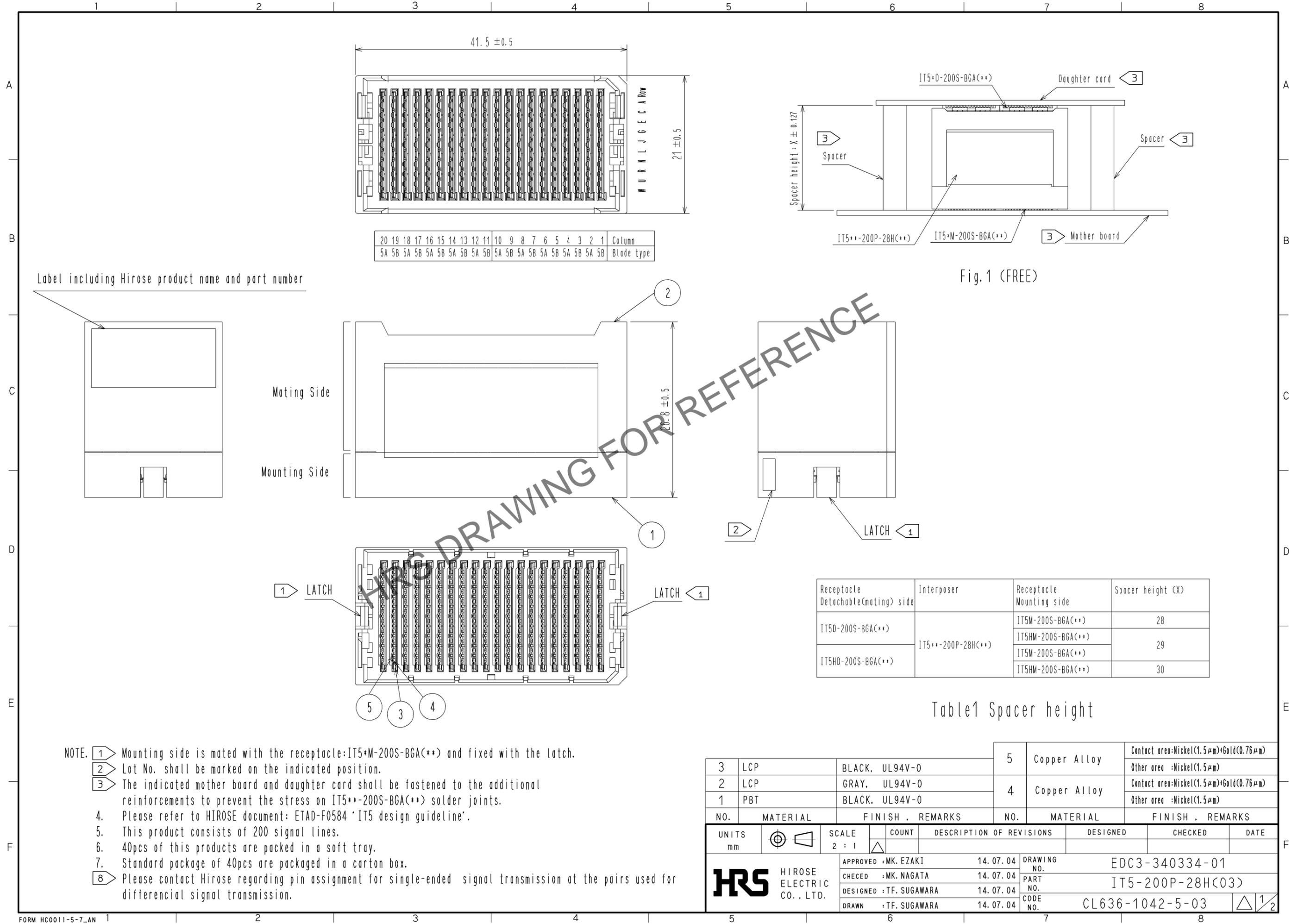


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 In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.



20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	Column
5A	5B	Blade type																		

Receptacle Detachable(mating) side	Interposer	Receptacle Mounting side	Spacer height (X)
IT5D-200S-BGA(**)	IT5** -200P-28H(**)	IT5M-200S-BGA(**)	28
		IT5HM-200S-BGA(**)	29
IT5M-200S-BGA(**)		30	
IT5HD-200S-BGA(**)			IT5HM-200S-BGA(**)

Table1 Spacer height

- NOTE.
- ① Mounting side is mated with the receptacle:IT5\*M-200S-BGA(\*\*) and fixed with the latch.
  - ② Lot No. shall be marked on the indicated position.
  - ③ The indicated mother board and daughter card shall be fastened to the additional reinforcements to prevent the stress on IT5\*\* -200S-BGA(\*\*) solder joints.
  - 4. Please refer to HIROSE document: ETAD-F0584 'IT5 design guideline'.
  - 5. This product consists of 200 signal lines.
  - 6. 40pcs of this products are packed in a soft tray.
  - 7. Standard package of 40pcs are packaged in a carton box.
  - ⑧ Please contact Hirose regarding pin assignment for single-ended signal transmission at the pairs used for differential signal transmission.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	LCP	BLACK	UL94V-0	5	Copper Alloy		Contact area:Nickel(1.5μm)+Gold(0.76μm) Other area :Nickel(1.5μm)
2	LCP	GRAY	UL94V-0	4	Copper Alloy		Contact area:Nickel(1.5μm)+Gold(0.76μm) Other area :Nickel(1.5μm)
1	PBT	BLACK	UL94V-0				

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△	APPROVED : MK. EZAKI 14.07.04			
HIROSE ELECTRIC CO., LTD.			CHECED : MK. NAGATA 14.07.04	DRAWING NO. EDC3-340334-01		
			DESIGNED : TF. SUGAWARA 14.07.04	PART NO. IT5-200P-28H(03)		
			DRAWN : TF. SUGAWARA 14.07.04	CODE NO. CL636-1042-5-03		
				1/2		

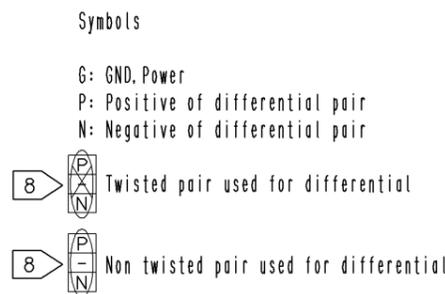
A  
B  
C  
D  
E  
F

Wafer type		Wafer #	
IT5 wafer B (100 ohm)	IT5 wafer A (100 ohm)	Column	Row
		20	40
		19	39
		18	38
		17	37
		16	36
		15	35
		14	34
		13	33
		12	32
		11	31
		10	30
		9	29
		8	28
		7	27
		6	26
		5	25
		4	24
		3	23
		2	22
		1	21
			20
			19
			18
			17
			16
			15
			14
			13
			12
			11
			10
			9
			8
			7
			6
			5
			4
			3
			2
			1
			X
			Y

IT5\*M-200S-BGA(\*\*) Pin assignment footprint for mounting side

Wafer type		Wafer #	
IT5 wafer B (100 ohm)	IT5 wafer A (100 ohm)	Column	Row
		20	40
		19	39
		18	38
		17	37
		16	36
		15	35
		14	34
		13	33
		12	32
		11	31
		10	30
		9	29
		8	28
		7	27
		6	26
		5	25
		4	24
		3	23
		2	22
		1	21
			20
			19
			18
			17
			16
			15
			14
			13
			12
			11
			10
			9
			8
			7
			6
			5
			4
			3
			2
			1
			Y
			W
			V
			U
			T
			R
			P
			N
			M
			L
			K
			J
			H
			G
			F
			E
			D
			C
			B
			A
			X

IT5\*D-200S-BGA(\*\*) Pin assignment footprint for mating side



<b>HRS</b>	DRAWING NO.	EDC3-340334-01
	PART NO.	IT5-200P-28H(C03)
	CODE NO.	CL636-1042-5-03